

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

H. ARAI et al

Serial No.

Filed: March 7, 2002

For: A SEMICONDUCTOR DEVICE AND METHOD OF
MANUFACTURING THE SAME

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows.

IN THE ABSTRACT

Page 76 and 77, "Abstract of the Disclosure" section, delete this section in its entirety and replace with:

A semiconductor chip has a quadrangle main surface, a wiring substrate, and a resin seal member for sealing the semiconductor chip, in which the resin seal member has a quadrangle main surface which confronts the main surface of the semiconductor chip. A gate cut trace portion is formed on a side face extending along a first side of the main surface of the resin seal member. A sectional area of an area between the main surface of the wiring substrate and the main surface of the resin seal member at a position outside a side face of the semiconductor chip is smaller than a sectional area of an